Amphenol

Enabling The Electronics Revolution

OverPass™ Solutions

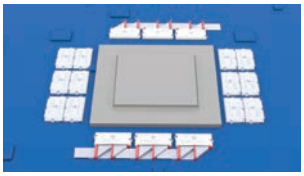
Cable system offering a broad range of capabilities that efficiently take high speed signal from near the ASIC to anywhere in the system.

www.amphenol-icc.com/overpass

External High Speed IO

Near ASIC to
external IO receptacles

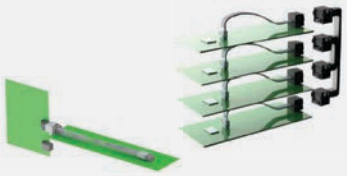
- High speed interconnect link from the chip site directly to the external IO port
- HSIO OverPass product portfolio fully compliant to established industry standard interfaces: SFP, QSFP, QSFP DD, OSFP and others
- Supports signal transmission speeds of 10G, 28G, 56G PAM4 and 112G per lane bandwidths
- Press fit or cabled sideband signal management; ; engineered wire management
- Stacked, ganged, and belly-to-belly HSIO connector and cage configurations with high density (DP/mm2) near chip / on chip solutions



Internal

Near ASIC to cards or
board location in system

- Delivering a simple, low-loss, direct link to pluggable modules or anywhere in your system
- Optimization with our high speed, low loss twinax cable with high speed connectors such as: Mini-SAS HD, OCulink, SlimSAS™, Mini Cool Edge IO, ExtremePort™ Z-Link, Flash & Swift, and micro-LinkOVER™
- Solutions are available in 10G, 25G, 56G & 112G PAM4 per lane signaling speeds
- Multiple cable exit options like straight, right angle, and coplanar
- Construction options including double ended, Y, and breakout cables.
- Single, ganged and stacked cage configurations



Cabled Backplane

Near ASIC to system backplane
or coplanar cards

- Cable Backplane System portfolio products extend the reach of passive copper for next generation system designs
- 56G and 112G PAM4 performance
- Optimization with our high speed, low loss twinax cable with Paladin® and ExaMAX® backplane connector families
- Flexible connector architecture supports cable blind mating with a backplane cable, press fit headers, right angle and orthogonal configurations

High Speed Bulk Cables

High frequency SkewClear EXD
cable technology

- Offerings include multi-pair cables: 2, 4 and 8 pair constructions in wire gages from 32 AWG to 26 AWG (34 AWG in development)
- Supports transmission speeds of 10G, 28G, 56G, and 112G PAM4 per lane bandwidths
- Impedance tuned designs support: Paladin ®, ExaMAX®, ExaMAX+®, micro-LinkOVER™, Swift, Flash, GenZ, OverPass™ HSIO
- FEP insulated wiring for higher temperature environments